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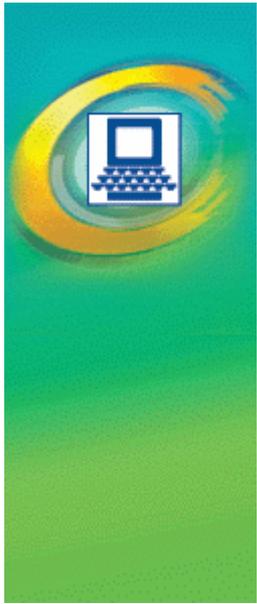
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News

News » 09/11/2006 until 23/04/2007

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- AMD Barcelona

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News items

GeIL's New Esoteria Series

Author: Martin Brijs
Publication: 23/04/2007 4:38
News type: Product news
Source: Geil USA

GeIL USA has recently announced the new "Esoteria Series". Esoteria, or Esoteric, means "*specialized or advanced in nature, available only to a narrow circle of people that are highly knowledgeable*".

Like the name suggests, this Series of memory is specialized in nature, designed with the enthusiasts in mind. Racing-inspired, the Esoteria Series is screaming for speed while boasting real carbon-fiber integrated onto the heat-spreaders. The carbon fiber is made by renowned aftermarket BMW Tuner-Vorsteiner with dry vacuumed form inspired by F1 racing technology. This is no wannabe imitation of fake carbon fiber. Each of the Esoteria carbon fiber heat-spreader requires being hand crafted for proper fitment. GeIL didn't just stop at the looks. After all, it is what's under the hood that counts. Optimized SPD to couple with the high-grade chips used in the Esoteria, overclockability has been increased while retaining stability. Due to the advanced and complexity nature of this product, it will be shipped in limited quantities.

Esoteria Series
 VORSTEINER technik



Specifications:

- * Available in DDR2 PC2-6400 800MHz & DDR2 PC2-8500 1066MHz
- Capacity of 2GB Dual Channel (2x1GB)
- CAS 4-4-4-12
- Optimized SPD for overclocking
- Voltage 2.1V - 2.5V
- Black or Silver true carbon-fiber with Heat-spreader

- Black or Silver aluminum base heat-spreaders
- GeIL Limited Lifetime Warranty

0 comment

G.Skill unveils new DDR2-1066 CL5 Memory Module

Author: Martin Brijs
Publication: 17/04/2007 9:06
News type: Product news
Source: G.Skill



G.Skill has launched some new DDR2 1066 modules. In addition to their DDR-1066 CL4 modules they have now also released DDR-2-1066 CL5 modules : F2-8500CL5D-2GBHK.



DDR2-1066 HK Series Features:

- Guaranteed clock speed of 1066MHz (PC2-8500)
- Low latency settings of 5 (CL), 5 (TRCD), 5 (TRP), 15 (TRAS)
- Lifetime warranty
- Available in the following packages:
 F2-8500CL5S-1GBHK - Single Module of 1GB
 F2-8500CL5D-2GBHK - Matched Pair of 2 * 1GB modules (2GB kit)

These single packed modules will be available through G.Skill's authorized resellers and distributors worldwide. For more information and specifications of the new PK series products, please visit the G.Skill [website](#)

0 comment

Apacer DDR2 powers Apple Xserve

Author: Richard Schouw
Publication: 13/04/2007 6:24
News type: Product news
Source: Apacer



Apacer continues its Apple support with DDR2 667 MHz FB-DIMM for Apple's Xserve 1U server. In capacities up to 4GB, these modules should fulfil the Apple Xserve's high capacity needs.

Apple's fifth-generation 1U server, the new Xserve, combines two power-efficient Dual-Core 64-bit Intel Xeon

processors up to 3.0GHz with Mac OS X Server. The performance is 5 times faster than the Xserve G5. The high-bandwidth architecture includes two PCI Express x8, independent 1.33GHz frontside bus per processor, 4MB of shared L2 cache and eight DIMM slots supporting up to 32GB of DDR2 667 MHz FB-DIMM modules. In addition, the new Xserve's IO bandwidth is four times higher than Apple Xserve G5, with 3 times faster memory bandwidth and 2 times greater storage bandwidth. As one of the original companies that is working closely with Intel on FB-DIMM development, Apacer is ready to support state-of-the-art systems, like the Apple Xserve taking advantage of FB-DIMM technology.



In order to make sure that Apacer's FB-DIMM works perfectly with Apple Xserve for compatibility and stability, all Apacer FB-DIMM modules need to pass actual Xserve full load testing. The DDR2 FB-DIMM capacity is 512MB, 1GB, 2GB and 4GB. With the eight DIMM slots fully loaded, the highest capacity can go up to 32GB. As a choice for purchasing the FB-DIMM modules directly from Apple, Apacer provides Apple Xserve users with an attractive business alternative with a lower cost solution, that should guarantee 100% compatibility and great reliability. This module includes a lifetime warranty along with Apacer's global support.

0 comment

Crucial announces new Ballistix and Ballistix Tracer Modules

Author: Martin Brijs
Publication: 11/04/2007 3:33
News type: Product news
Source: Crucial



Crucial has just introduced some new arrivals to their enthusiastic "Ballistix" line. The new PC8500 memory operates at 1066MHz on latencies of 5-5-5-15 and 2.2V. These are available in the normal Ballistix casing as well as the "Tracer" variety. The Tracer modules have LEDs that flash according to the memory activity of the system, and is a cool feature when you have a side window.



The modules are available immediately, prices are £ 273,76 for a 2GB Tracer kit and £ 266,71 for a plain 2GB kit without LEDs. More info can be found on the Crucial [website](#).

0 comment

Super Talent: 4 GB DDR2-800 Gaming Kit

Author: Richard Schouw
Publication: 27/03/2007 6:19
News type: Product news
Source: Super Talent



Super Talent announced a new 4 GigaByte 800MHz DDR2 memory kit that should be ideal for gamers and enthusiasts.

The new T800UX4GC5 is a matched pair of 2 GigaByte 800MHz DDR2 non-ECC unbuffered 240-pin DIMMs. This kit has been tested and is guaranteed to operate at 800MHz in a dual channel motherboard at 5-5-5-15 latencies at 2.1 Volts. Each module is constructed using sixteen 128Mbit x 8 FBGA chips organized into a dual-rank 256M x 64 module, and clad in Super Talent's blue cast aluminum HE heatspreader.



These modules are manufactured and tested in Super Talent's Silicon Valley factory. Every Super Talent module built is hand tested in a motherboard under load to ensure the highest level of reliability. The T800UX4GC5 kit will be available this week at an estimated street price of \$438.

0 comment

DDR2 1066 overclocking modules introduced by Kingmax

Author: Martin Brijs
Publication: 08/03/2007 11:00
News type: Product news
Source: Kingmax



Kingmax recently introduced new overclocking modules that work at a default speed of 1066 MHz. With motherboards now supporting FSB speeds and memory speeds up to 1333MHz like the new 680i chipset by nVidia the expectation is that most DDR2 memory modules in the near future will be 1066MHz as standard.



The new "Mars" modules by Kingmax come in a 512MB and a 1GB module, and use Nanya chips. Kingmax even promises a minimum overclocking headroom of 10% on the modules, so good news for overclockers.

The modules are available in shops soon, a price has not yet been disclosed.

0 commen

Samsung starts DRAM producing at 60nm

Author: Richard Schouw
Publication: 01/03/2007 5:03
News type: Product news
Source: Samsung



Samsung announced that it has begun mass producing the industry's first 1Gigabit DDR2 DRAM using 60 nanometer class process technology.

Use of the new process technology is a significant milestone in that it increases production efficiency by 40 percent over the 80nm process technology deployed in DRAM fabrication since early 2006, and offers twice the productivity of 90nm general process technology.

Ample market availability of 1Gb DRAM will further increase the demand for large density DRAMs, especially as the new premium Vista operating system imposes a DRAM requirement of at least 1Gigabyte (GB). Samsung's extensive line up of 60nm 1Gb DRAM-based modules includes 512MB, 1GB and 2GB densities supporting either 667Mbps or 800Mbps speeds with customer validation.

Samsung anticipates such a high degree of receptivity to the 60nm process that it should drive greater demand for 1Gb DRAM chips in the near future over today's mainstream density of 512Mb. In addition to its 60nm process technology innovation, Samsung's use of metal-insulator metal (MIM) for its capacitors provides enhanced data storage in sub-70nm designs.

Furthermore, the use of a recently-announced selective epitaxial growth (SEG) technology provides for a broader electron channel, and optimizes the speed of each chip's electrons to reduce power consumption and enable higher performance.

The 60nm process is expected to become the mainstream circuit technology for DRAM in 2008. In the first year of market availability alone, 60nm DRAM revenues are expected to reach US \$2.3billion worldwide and further increase to US \$32 billion by 2009.

0 commen

Samsung clocks GDDR4 at 4 GHz

Author: Wouter van den Abeelen
Publication: 27/02/2007 9:17
News type: Product news



Samsung has presented new GDDR4 memory chips at the ISSCC event. The new chips are clocked at 4 GHz, more than 40% faster than the original frequencies that Samsung was aiming at. The 512 Mbit (64 MB) chips are manufactured in a 80 nm proces and require a voltage between 1.4 and 2.1 Volt. Samsung used 2.0 Volt to run the chips stable at 4.0 Ghz.

GDDR4 at 4 GHz delivers a bandwidth of 16 GB/s. With 256 bit memory controllers on video cards the new memory will result in an astounding bandwith of 128 GB/s. Originally GDDR4 was planned to scale up to 2.8 GHz in 2007, while GDDR5 was planned to go beyond 3.5 GHz. With Samsung new chips it seems that the life cycle of GDDR4 will be much longer.

More info can be found at [Xbitlabs](#).

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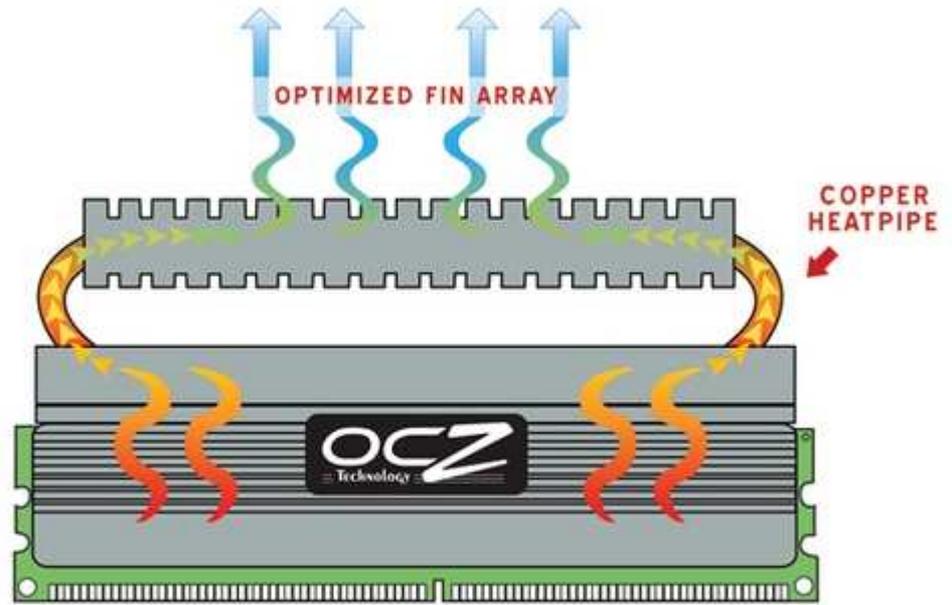
OCZ introduces "Reaper" overclock memory

Author: Jan-Willem Hopman
Publication: 27/02/2007 9:01
News type: Product news



OCZ has introduced new memory modules called 'Reaper' featuring special HPC (Heat Pipe Conduit) cooling. This radical new memory cooling solution utilizes a heatpipe to transfer the heat to a separate heatsink that can benefit from the airflow produced by the CPU-cooler. OCZ offers the modules in 2 GB dual channel kits, with a default speed rating of 1066 MHz at 5-5-5-15 latencies. The overclock potential is very high according to the developers. The modules are equipped with SPD and EEP: this last technology makes sure the modules always run at optimal speed in systems with nVidia chipset. With this technology you don't have to be a die-hard overclocker to get the most performance out of your modules. [Here's](#) more information on the new modules.





SUPERIOR HEAT DISSIPATION VIA COPPER HEATPIPE AND COMBINATION ALUMINUM HEATSPREADER/FIN ARRAY DESIGN

0 commen

OCZ introduces PC2-6400 FlexXLC memory series

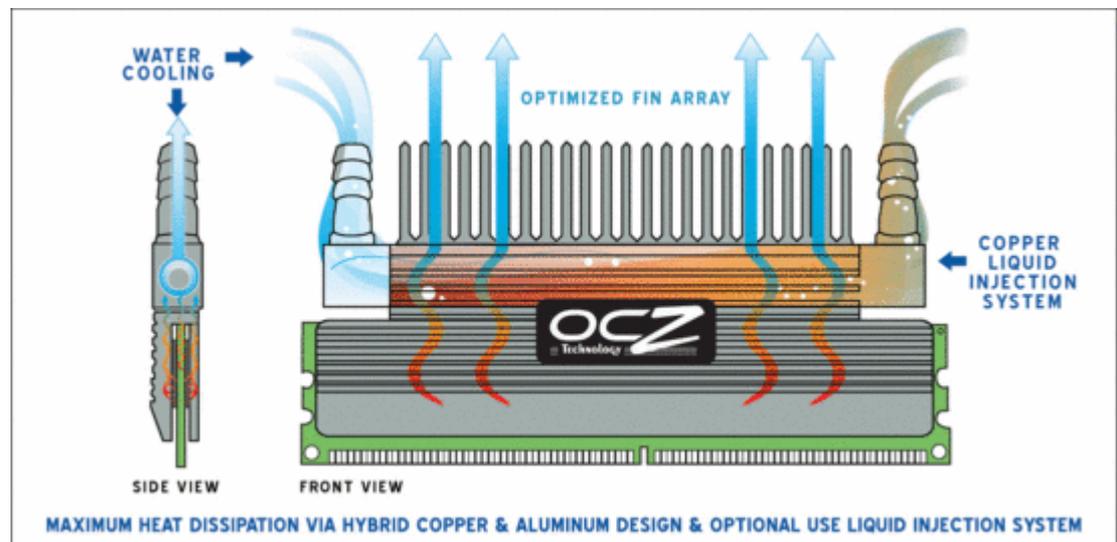
Author: Richard Schouw
Publication: 19/01/2007 1:24
News type: Product news
Sources: Hardwaresecrets / OCZ



OCZ announces the latest addition to the Premium Flex Memory Series, the PC2-6400 FlexXLC. These new DDR2-800 modules feature the Flex XLC (Xtreme Liquid Convention) heatsink which delivers heat dissipation by hybrid copper and aluminum design alterable between passive air or water cooling. The modules have latencies of 4-4-4-15 and are available in 2 GB dual channel kits.



The PC2-6400 FlexXLC modules are optimized for the latest platforms and are part of OCZ's line-up of premium memory. The PC2-6400 series is backed by a Lifetime Warranty and technical support. The design of the OCZ PC2-6400 Flex XLC should be a complete, all-encompassing solution which should set a new standard for recreational enthusiasts.



Specifications

- 800MHz DDR2
- CL 4-4-4-15
- (CAS-TRCD-TRP-TRAS)
- Available in 2GB (2x1024) Dual Channel Kits
- Unbuffered
- OCZ Lifetime Warranty
- 2.0 Volts
- 240 Pin DIMM
- 2 x 1/4" ID (inner diameter) barbs
- FlexXLC Heatsink
- 2.2V EVP

G.Skill unveils DDR2-800 CL5 and DDR2-667 CL4 4GB kits

Author: Richard Schouw
Publication: 02/01/2007 12:45
News type: Product news
Source: G.Skill



G.Skill introduces a DDR2-800 CL5 4GB and DDR2-667 CL4 4GB memory kit.

**DDR2-667 PQ Series Features:**

- Guaranteed clock speed of 667MHz (PC2-5300)
- Low latency settings of 4 (CL), 4 (TRCD), 4 (TRP), 12 (TRAS)
- Lifetime warranty

Available in the following packages:

- F2-5300CL4S-2GBPQ - Single Module of 2GB
- F2-5300CL4D-4GBPQ - Matched Pair of 2 * 2GB modules (4GB kit)

DDR2-800 PQ Series Features:

- Guaranteed clock speed of 800MHz (PC2-6400)
- Low latency settings of 5 (CL), 5 (TRCD), 5 (TRP), 15 (TRAS)
- Lifetime warranty

Available in the following packages:

- F2-6400CL5S-2GBPQ - Single Module of 2GB
- F2-6400CL5D-4GBPQ - Matched Pair of 2 * 2GB modules (4GB kit)

Both single module and matched pair packages will be available through G.Skill's authorized resellers and distributors worldwide. For more information and specifications of the new PK series products, please visit <http://www.gskill.com/en/ddr2.html>

0 comment

TwinMOS launches TwiSTER DDR2-850

Author: Koen Wagenveld
Publication: 13/12/2006 8:03
News type: Product news
Source: Twimos



TwinMOS Technologies introduces the new TwiSTER DDR2-850 CL5 over-clocking DRAM modules after the earlier announced TwiSTER DDR2-800 CL5 and TwiSTER DDR2-1066 CL5. The 3 kinds of over-clocking modules are part of the TwiSTER series, and are specially designed to meet the demanding hardware requirements of over-clockers, advanced game players, and enterprise users. The TwiSTER series is the highest quality product line from TwinMOS Technologies, featuring reliable data access at fast speeds. Every module is tested to comply with the published specifications.



With specifications better than those of the current standard DDR2-800 model, the TwiSTER DDR2-850 CL5 uses lower CL values to enhance data transfer speed between the memory and the CPU, to meet the over-clocking requirements of consumers. New-generation, high-performance 90nm dies in a 64Mx8 configuration are used, along with the latest FBGA (Fine-Pitch Ball Grid Array) packaging technology, for both the 512MB and 1GB models. A JEDEC standard 6-layer PCB is used to stabilize data transfer signals. The high-performance heat-sink equipped on the module provides perfect cooling and electrical characteristics to enhance the work efficiency of the module.

TwinMOS Technologies provides a worldwide, lifetime warranty for all of its DRAM modules to assure product quality.

Product features:

- Frequency at 850MHz
- CL5
- High-performance aluminum heat-sink
- FBGA packaging assures better cooling and electrical characteristics

0 comment

Samsung introduces OneDRAM

Author: Richard Schouw
Publication: 13/12/2006 8:00
News type: Product news
Source: Samsung



Samsung announced that it has developed a prototype fusion memory chip that can significantly increase the data processing speed between processors in mobile applications.

Samsung's new fusion solution, OneDRAM, is expected to be specified in the design of handsets, game consoles and in other digital applications, especially those that use 3-dimensional graphics.

The 133MHz 512Mb device incorporates a dual-port approach to decrease the time that it takes to transfer data between processors. Data managed by the processors is housed in a shared bank where the space for storing the data can be adjusted accordingly. This meets the JEDEC, low power, double-data-rate (LPDDR) memory standard.

Along with the faster data processing speeds between the processors, the OneDRAM reduces power consumption by 30 percent, lessens the number of chips needed and minimizes area coverage by 50 percent, resulting in a five-fold increase in the speed of cell phone and gaming console operations, longer battery life and slimmer

handset designs.

A single OneDRAM can replace, at least, two mobile memories in high-end smart phones and other multimedia-rich handsets. In addition, by adjusting the hardware in the chipset, OneDRAM can cost-effectively reduce system circuitry, while maximizing overall operational efficiency.

Following the first fusion memory, OneNANDTM, this second generation of fusion memory technology from Samsung has effectively transformed the memory chip from a simple working memory to a component that enables dramatically improved system performance.

Samsung expects its OneDRAM to be introduced in handsets by the second half of 2007.

0 comment

Kingston releases 1200MHz DDR2 memory

Author: Martin Brijs
Publication: 07/12/2006 1:40
News type: Product news
Source: Tom's Hardware Guide



Tom's Hardware Guide has found out that Kingston is making a claim for the fastest DDR2 memory available at the moment. They have released HyperX PC9600 modules, running at a clockspeed of no less than 1200MHz. This announcement comes only two weeks after OCZ released their fastest memory, the FlexXLC PC9200.



The new modules will cost US\$ 525 for a 2 x 1GB kit, a 1GB module is US\$ 263 and 512MB module US\$ 139. They will offer a PC9200 variety as well, costing in at US\$ 518 for a 2GB kit, US\$ 259 for a 1GB module and US\$ 137 for a 512MB module.

0 comment

Corsair introduces 2GB DDR-667 FB-Dimms

Author: Martin Brijs
Publication: 07/12/2006 11:37
News type: Product news
Source: Corsair



Corsair today expanded its Fully Buffered DIMM (FB-DIMM) family of products to include new high density DDR2-667MHz speeds to support the latest dual-core Intel Xeon based platforms. Corsair high density high-speed FB-DIMMs offer enhanced memory throughput allowing for superior application responsiveness. Based on the JEDEC

standards, the new DDR2-667Mhz FB-DIMMs are designed to provide ultimate flexibility and expandability to balance capabilities of Intel dual core processors. Corsair claims every memory module is tested on Intel Xeon server platforms for maximum compatibility.



Specifications of the new modules:

- Low profile
- CRC and ECC error detection and correction
- 240-pin, Full Buffered dual inline memory module
- Ultra high density using 512MBit SDRAM devices
- Advanced Memory Buffer (AMB)
- JEDEC standard 1.5V high speed differential point-to-point link
- Four-bit prefetch architecture
- Off-chip driver (OCD) impedance calibration

The new 2GB modules are available now, the price per module is US\$ 379.

0 commen

AMD obtains license on Z-RAM Gen2

Author: Koen Wagenveld
Publication: 06/12/2006 8:05
News type: Product news
Source: Innovative Silicon



Innovative Silicon, the developer of Z-RAM high density memory, today announced availability of its second generation Z-RAM technology, named Z-RAM Gen2, which delivers significant performance improvements with greatly reduced power consumption. Simultaneously, the company is announcing that AMD has contracted to purchase a license for Z-RAM Gen2, having contracted to purchase a license to the previous generation technology in December of last year.

Z-RAM technologies achieve impressive density and performance by using a single transistor as a memory bitcell which is made possible by using SOI (silicon-on-insulator) wafers. Z-RAM Gen2 stores significantly more charge in the memory bitcell. The additional charge provides an order-of-magnitude improvement in both cell margin—the difference between a “1” and a “0”—and in data retention time. The higher margin also provides much faster data read and write times, yet reduces power consumption significantly. As a result, Z-RAM Gen2 significantly broadens the range of applications that can take advantage of Z-RAM’s density to both high-performance applications requiring greater than 1GHz operation (when pipelined), and low-power applications that require long-battery life.

Specs:

- Ultra-high density: greater than 5Mbits per mm² at 65nm, and greater than 10Mbits per mm² at 45nm (1.4x – 2x denser than eDRAM and 5x-6x denser than SRAM)
- High performance random array access: greater than 400MHz (when optimized for performance)
- Very low active power consumption: under 10µW/MHz (when optimized for low-power)

Z-RAM Gen2 technology has been fabricated and validated as a complete memory at 90nm, and the bitcell has been validated on an additional five fabrication processes. Test chips are currently in fabrication at both the 65nm and 45nm process nodes. The company has demonstrated bitcell operation on smaller geometries and on the emerging multi-gate/FinFET devices and anticipates no difficulty in scaling to sub45nm process technologies.

It is as of yet unknown what AMD will use the Z-RAM technology for, but it's not impossible that we'll see Z-RAM used as cache memory in upcoming CPU's.

0 commen

OCZ announces nVidia SLI memory

Author: Martin Brijs
Publication: 29/11/2006 2:25
News type: Product news
Source: OCZ



OCZ recently revealed the new and improved OCZ NVIDIA SLI -Ready branded memory product family. The new PC2-7200 SLI-Ready and PC2-8500 SLI-Ready modules now feature the first ever exclusively designed heatspreader for NVIDIA.

OCZ worked closely together with NVIDIA to optimize these modules specifically for current and next generation NVIDIA based platforms. As part of the NVIDIA SLI technology ecosystem, these modules undergo a rigorous series of tests by NVIDIA and are certified to provide performance-minded enthusiasts and gamers the quality, compatibility, and stability they seek when building an SLI gaming system.

With the innovative black XTC heatspreader and bold SLI-Ready logo, the new OCZ SLI-Ready series allows gamers and system builders to build a system that showcases the elite performance of SLI certified platforms, a selection of "interoperable components," all of which elevate the standards of performance for enthusiasts and gamers when operating together in the same system.



"OCZ and NVIDIA have been working closely together to deliver the ultimate experience to high-end consumers with the new SLI-Ready series of modules," commented Dr. Michael Schuette, VP of Technology Development,

OCZ Technology Group. "Through our cooperation, we are able to deliver a customized solution for NVIDIA gamers, enthusiasts, and SI's, one that addresses both the EPP memory performance and cooling requirements with a solution that is tailor made specifically for these customers."

As an SLI-certified memory product, the PC2-8500 and PC2-7200 memory modules are built with an EPP (Enhanced Performance Profiles) programmed SPD to provide a true Plug and Play overclocking feature that eliminates the need for manual configuration and makes memory optimization easy for the complete range of consumers. These are just the first two of many SLI-Ready parts that will be released in this series.

All SLI-Ready memory is 100% hand-tested for quality assurance and furthermore, each OCZ SLI-Ready module is backed by the industry leading OCZ Lifetime Warranty and technical support for unparalleled peace of mind.

For more information on the new OCZ SLI-Ready DDR2 series, please visit the [OCZ product page](#).

0 commen

TwinMOS announces DDR2-667 Very-Low-Profile Memory DIMM

Author: Martin Brijs
Publication: 28/11/2006 11:45
News type: Product news
Source: Twinmos



TwinMOS recently announced high-capacity VLP (very low profile)-DIMMs for blade servers. As a blade server is an ultra thin device, conventional memory will not fit in the slots in a blade server. The VLP DIMMS are especially designed to be used with these servers without compromising performance.



This new VLP-DIMMs is offered in a high-capacity (2GB) size and uses new-generation DDR2 dies in a 128Mx4x36 configuration on a micro PCB measuring 133.35 (W) x 18.3 (H) mm. Since the VLP module is only 60% as tall as a typical server DIMM, it helps to enhance memory expandability and cooling inside the server. This VLP-DIMMs is suitable for use in vertically deployed memory slots, such as servers and workstations using the Intel E7520/E7525 Chipset, Intel E7320 Chipset and the new generation AMD CPUs.

The modules come with Twinmos' usual lifetime warranty. More information can be found on the [TwinMOS website](#).

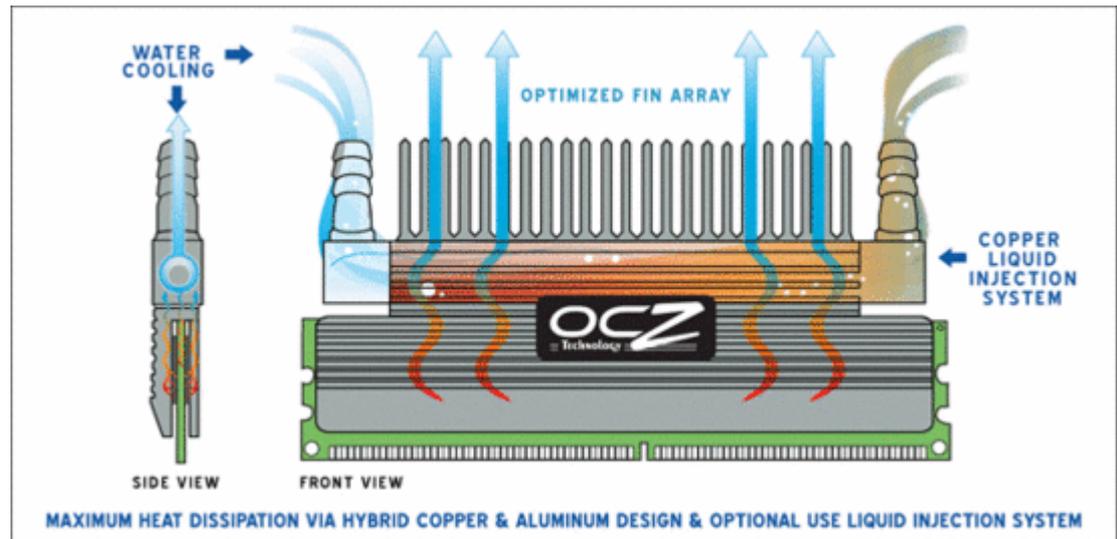
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OCZ unveils FlexXLC memory modules

Author: Martin Brijs
Publication: 21/11/2006 11:35
News type: Product news
Source: OCZ



OCZ today unveiled the OCZ PC2-9200 FlexXLC 2x1GB Kit, a revolutionary new memory solution that offers unprecedented speed, signal integrity, and thermal management. These new modules feature the new OCZ FlexXLC heatsink that delivers superior heat dissipation via a hybrid copper and aluminum design alterable between passive air or water cooling. As the World's fastest DDR2, the PC2-9200, in combination with the innovative FlexXLC technology, is considerably the most ground-breaking and unique memory product existing today.



In order to cope with the extra heat generated by DDR2 modules running at 2.1V or even higher OCZ has come up with a unique concept to keep the modules cooler. The FlexXLC modules feature a heatsink that can be used as is, or connected to a watercooling system.

Thanks to OCZ's FlexXLC (Xtreme Liquid Convention) heat management solution, the OCZ PC2-9200 operates at extreme speeds of 1150MHz without the high temperatures that inhibit or damage the module's ICs. The FlexXLC module was engineered with a unique "flexible" design which gives enthusiasts the option to run the modules passively or water cooled via the integrated liquid injection system. The concurrent use of both technologies (water-cooling) promotes maximum heat dissipation. "Water-cooling is more efficient than air cooling, yet standard memory kits are usually not available in off-the-shelf water-cooled configurations," commented Dr. Michael Schuette, VP of Technology Development at OCZ Technology Group. "The new OCZ FlexXLC series- featuring an exciting, novel hybrid water and air cooler based on OCZ's embedded copper liquid injection system- pushes thermal management of memory modules one step further to keep up with the ever-increasing frequency demands. Moreover, the FlexXLC modules seamlessly co-migrate with any system upgrade to liquid cooling."



Among these thermal management advantages, the PC2-9200 FlexXLC also implements a new 8-layer PCB with thermally conductive power and ground planes to guide heat away from the interconnects with the memory ICs. This facilitates less "crosstalk," consequently enhancing the module's total signal integrity. The blend of 8-layer PCB technology and the FlexXLC surface cooler truly offers a state-of-the-art design for the extremist.

The PC2-9200 FlexXLC modules are optimized for the latest cutting edge platforms and will be available in 2GB

(2x1024MB) dual channel kits. As part of OCZ's line-up of premium memory, the PC2-9200 series is backed by a Lifetime Warranty and industry-leading technical support. Harnessing the achievement of leading-edge speed, high performance heat dissipation, and enhanced signal integrity, the unparalleled design of the OCZ PC2-9200 FlexXLC is a complete, all-encompassing solution certain to set a new benchmark in enthusiast memory.

Complete specifications on the FlexXLC modules can be viewed on the OCZ [product page](#)

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TwinMOS launches 4GB miniSDHC

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After releasing 8GB SDHC cards in October, TwinMOS launches 4GB miniSDHC cards to meet the high capacity market trend. SDHC (SD High Capacity) is defined by the SD association. The capacity of SDHC is increased from 4GB to 32GB indicated by three levels including: Class2, Class4 and Class6.



TwinMOS's 4GB miniSDHC card is only 21.5x20x1.4mm and can hold up to 2,000 photos and over 1,000 songs. The miniSDHC supports the SD2.0 specification and is compatible with SD slots using an adapter. Low power consumption and single/dual channel with high performance means these cards are ideal for digital media players. The miniSDHC card can however only be used in devices that support the standard, among which several DVs, PDAs, etc.

Specifications:

- Supports SD memory card specification v2.0
- Supports CPRM
- Low power consumption: supports 3.3V
- Single/Dual Channel
- Support SDHC Host specification
- Capacity : 4GB ~32GB
- Dimension : 21.5(L) x 20(W) x 1.4(H) mm
- Weight : 0.8g ± 5%

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